BSS84AKT

50 V, 150 mA P-channel Trench MOSFET

Rev. 1 — 23 May 2011 **Product data sheet**

1. Product profile

1.1 General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT416 (SC-75) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

1.2 Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology
- ESD protection up to 1 kV
- AEC-Q101 qualified

1.3 Applications

- Relay driver
- High-speed line driver
- High-side loadswitch
- Switching circuits

## 1.4 Quick reference data

Table 1. Quick reference data
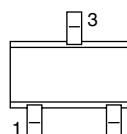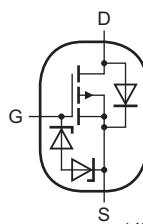
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	T_j = 25 °C	-	-	-50	V
V_{GS}	gate-source voltage		-20	-	20	V
I_D	drain current	V_{GS} = -10 V; T_{amb} = 25 °C [1]	-	-	-150	mA
Static characteristics						
R_{DSon}	drain-source on-state resistance	V_{GS} = -10 V; I_D = -100 mA; T_j = 25 °C	-	4.5	7.5	Ω

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2.

2. Pinning information

Table 2.   Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	S	source		
3	D	drain	SOT416 (SOT416)	sym146

3. Ordering information

Table 3.   Ordering information

Type number	Package		
	Name	**Description**	**Version**
BSS84AKT	SOT416	plastic surface-mounted package; 3 leads	SOT416

4. Marking

Table 4.   Marking codes

Type number	Marking code[1]
BSS84AKT	Z6

[1]   % = placeholder for manufacturing site code

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5.   Limiting values

Table 5.   Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	T_j = 25 °C		-	-50	V
V_{GS}	gate-source voltage			-20	20	V
I_D	drain current	V_{GS} = -10 V; T_{amb} = 25 °C	[1]	-	-150	mA
		V_{GS} = -10 V; T_{amb} = 100 °C	[1]	-	-95	mA
I_{DM}	peak drain current	T_{amb} = 25 °C; single pulse; t_p ≤ 10 µs		-	-0.6	A
P_{tot}	total power dissipation	T_{amb} = 25 °C	[2]	-	250	mW
			[1]	-	300	mW
		T_{sp} = 25 °C		-	770	mW
T_j	junction temperature			-55	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C
Source-drain diode						
I_S	source current	T_{amb} = 25 °C	[1]	-	-150	mA
ESD maximum rating						
V_{ESD}	electrostatic discharge voltage	HBM	[3]	-	1000	V

[1]   Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2.

[2]   Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3]   Measured between all pins.
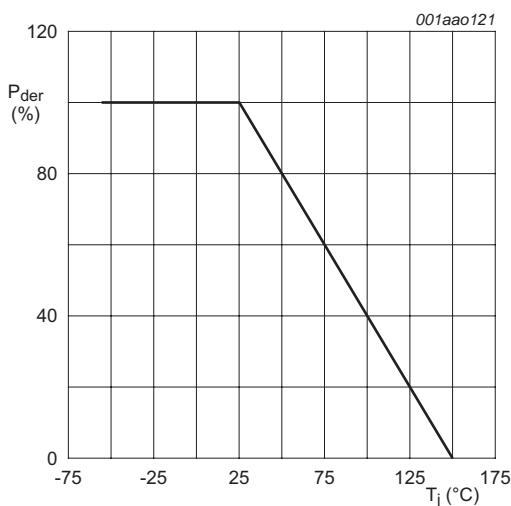
$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\%$$

Fig 1.   Normalized total power dissipation as a function of junction temperature
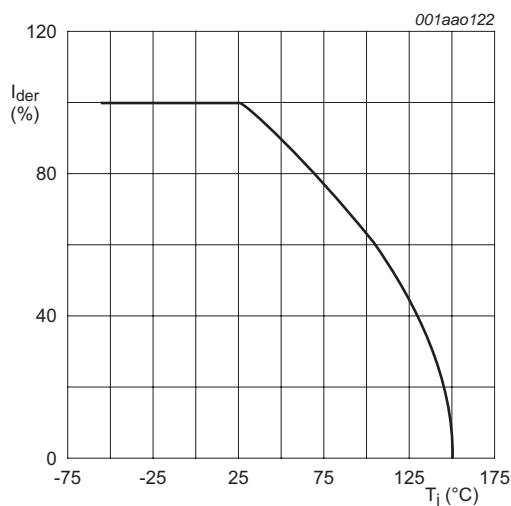
$$I_{der} = \frac{I_D}{I_{D(25°C)}} \times 100\%$$

Fig 2.   Normalized continuous drain current as a function of junction temperature

I_{DM} is single pulse

(1) t_p = 1 ms

(2) t_p = 10 ms

(3) DC; T_{sp} = 25 °C

(4) t_p = 100 ms

(5) DC; T_{amb} = 25 °C; drain mounting pad 1 cm^2

Fig 3.　Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

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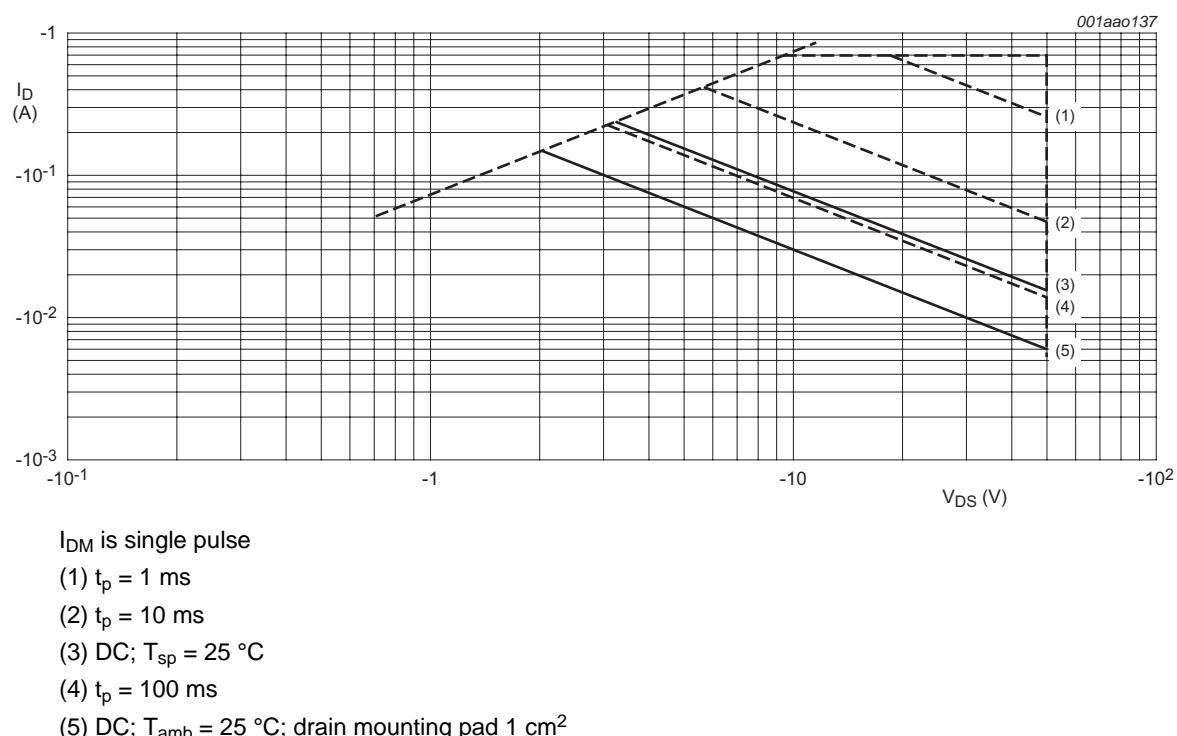
6. Thermal characteristics

Table 6. **Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	440	510	K/W
			[2]	-	360	415	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	160	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2.
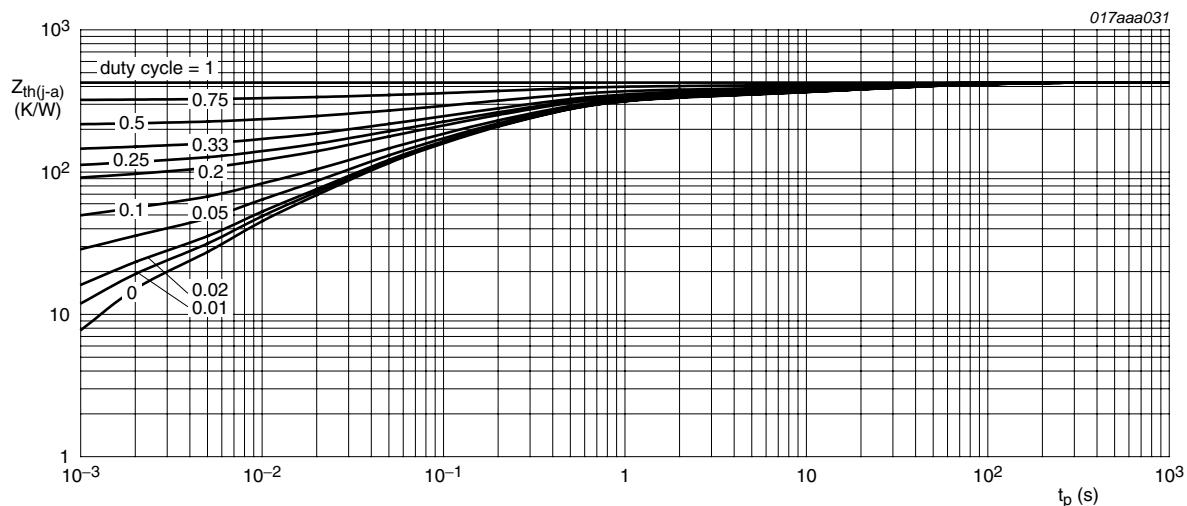
FR4 PCB, standard footprint

Fig 4. **Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**
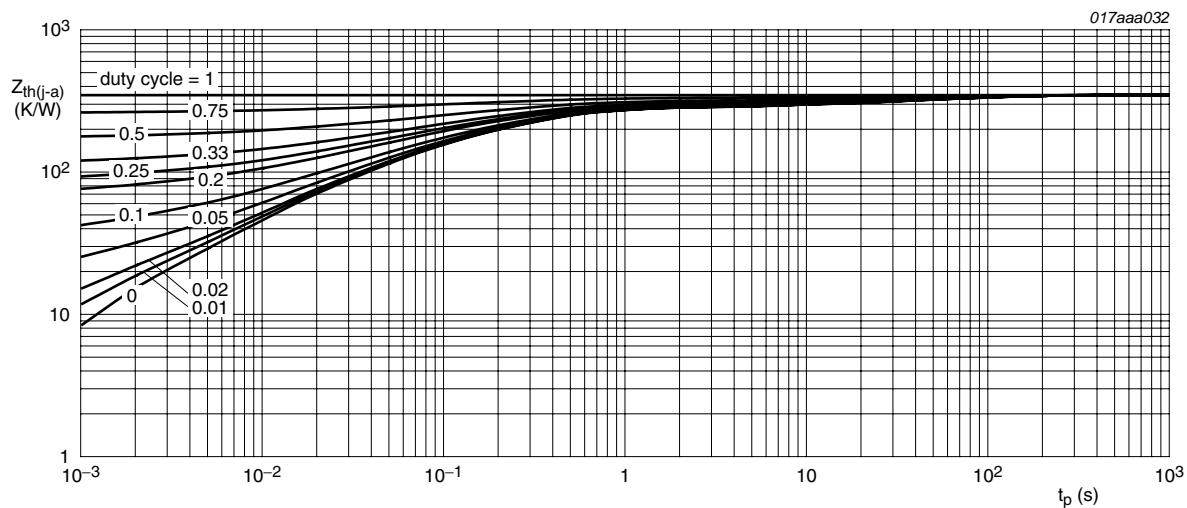
FR4 PCB, mounting pad for drain 1 cm^2

Fig 5. **Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

7. Characteristics

Table 7.   Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = -10 μA; V_{GS} = 0 V; T_j = 25 °C	-50	-	-	V
V_{GSth}	gate-source threshold voltage	I_D = -250 μA; V_{DS} = V_{GS}; T_j = 25 °C	-1.1	-1.6	-2.1	V
I_{DSS}	drain leakage current	V_{DS} = -50 V; V_{GS} = 0 V; T_j = 25 °C	-	-	-1	μA
		V_{DS} = -50 V; V_{GS} = 0 V; T_j = 150 °C	-	-	-2	μA
I_{GSS}	gate leakage current	V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C	-	-	-10	μA
		V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 °C	-	-	-10	μA
R_{DSon}	drain-source on-state resistance	V_{GS} = -10 V; I_D = -100 mA; T_j = 25 °C	-	4.5	7.5	Ω
		V_{GS} = -10 V; I_D = -100 mA; T_j = 150 °C	-	8	13.5	Ω
		V_{GS} = -5 V; I_D = -100 mA; T_j = 25 °C	-	5.7	8.5	Ω
g_{fs}	forward transconductance	V_{DS} = -10 V; I_D = -100 mA; T_j = 25 °C	-	150	-	mS
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	V_{DS} = -25 V; I_D = -200 mA; V_{GS} = -5 V; T_j = 25 °C	-	0.26	0.35	nC
Q_{GS}	gate-source charge		-	0.12	-	nC
Q_{GD}	gate-drain charge		-	0.09	-	nC
C_{iss}	input capacitance	V_{DS} = -25 V; f = 1 MHz; V_{GS} = 0 V; T_j = 25 °C	-	24	36	pF
C_{oss}	output capacitance		-	4.5	-	pF
C_{rss}	reverse transfer capacitance		-	1.3	-	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = -30 V; R_L = 250 Ω; V_{GS} = -10 V; $R_{G(ext)}$ = 6 Ω; T_j = 25 °C	-	13	26	ns
t_r	rise time		-	11	-	ns
$t_{d(off)}$	turn-off delay time		-	48	96	ns
t_f	fall time		-	25	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	I_S = -115 mA; V_{GS} = 0 V; T_j = 25 °C	-0.48	-0.85	-1.2	V
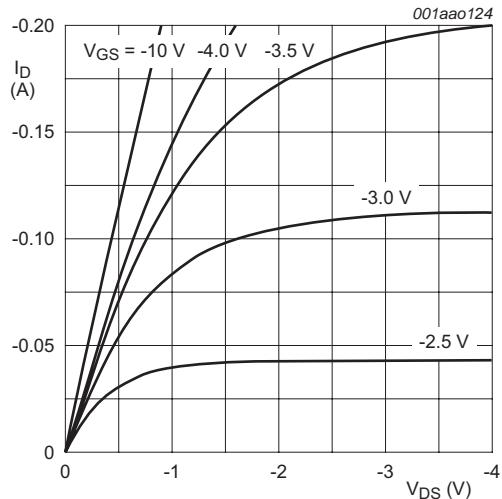
**Fig 6.** Output characteristics; drain current as a function of drain-source voltage; typical values

$T_j = 25\ °C$

$T_j = 25\ °C$; $V_{DS} = -5\ V$

(1) minimum values

(2) typical values

(3) maximum values
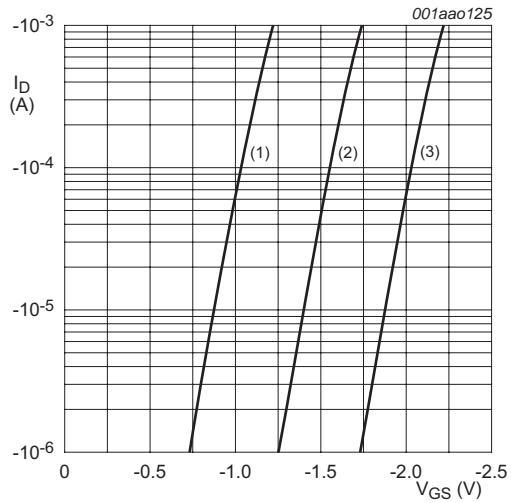
Fig 7. Sub-threshold drain current as a function of gate-source voltage

$T_j = 25\ °C$

(1) $V_{GS} = -3.0\ V$

(2) $V_{GS} = -3.5\ V$

(3) $V_{GS} = -4.0\ V$

(4) $V_{GS} = -5.0\ V$

(5) $V_{GS} = -10.0\ V$
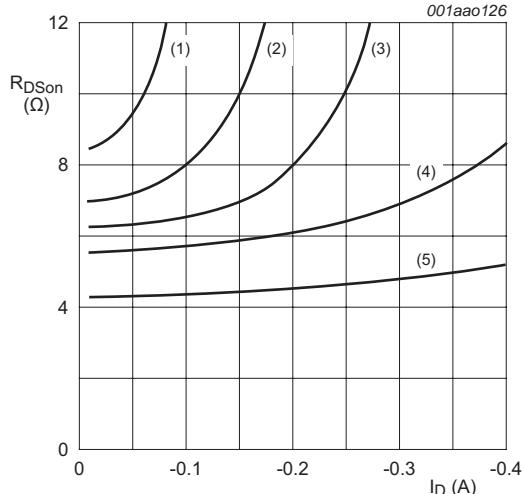
Fig 8. Drain-source on-state resistance as a function of drain current; typical values

$I_D = -200\ mA$
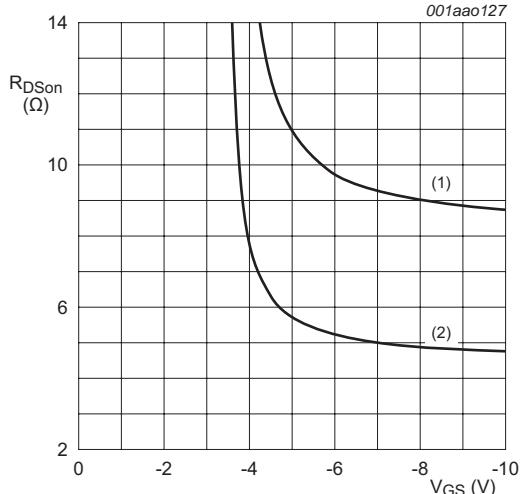
(1) $T_j = 150\ °C$

(2) $T_j = 25\ °C$

**Fig 9.** Drain-source on-state resistance as a function of gate-source voltage; typical values
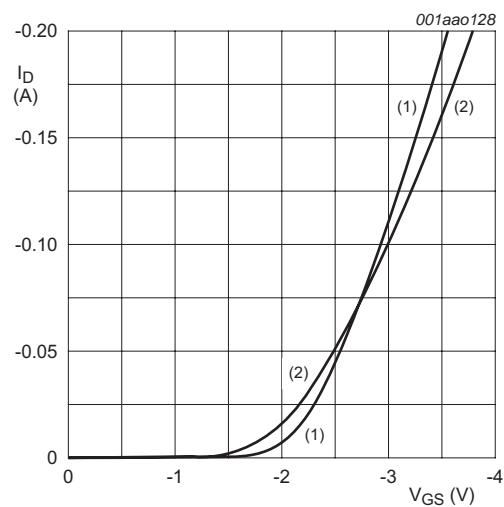
$V_{DS} > I_D \times R_{DSon}$

(1) $T_j = 25$ °C

(2) $T_j = 150$ °C

**Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values**
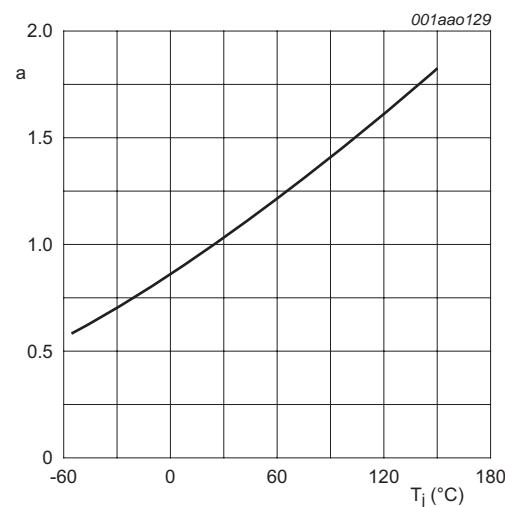
$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

Fig 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values
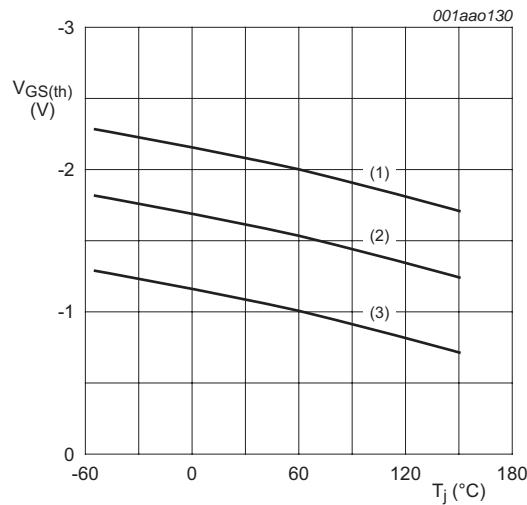
$I_D = -0.25$ mA; $V_{DS} = V_{GS}$

(1) maximum values

(2) typical values

(3) minimum values

Fig 12. Gate-source threshold voltage as a function of junction temperature
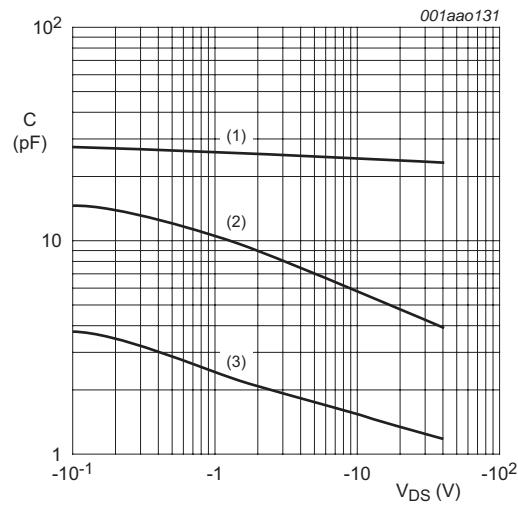
$f = 1$ MHz, $V_{GS} = 0$ V

(1) C_{iss}

(2) C_{oss}

(3) C_{rss}

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

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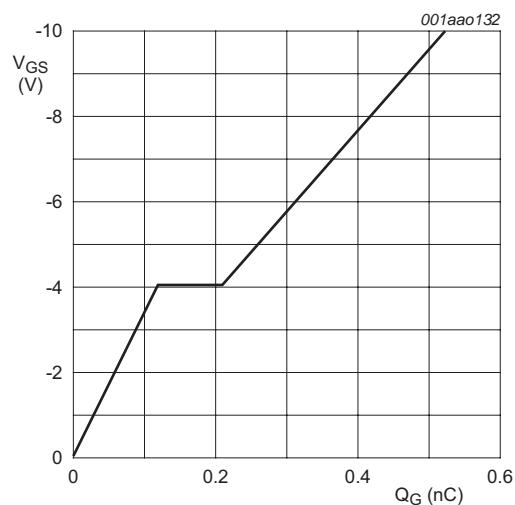
I_D = -0.2 A; V_{DS} = -25 V; T_{amb} = 25 °C

Fig 14. Gate-source voltage as a function of gate charge; typical values
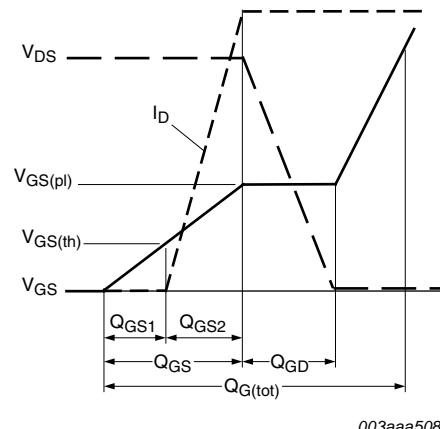

Fig 15. Gate charge waveform definitions
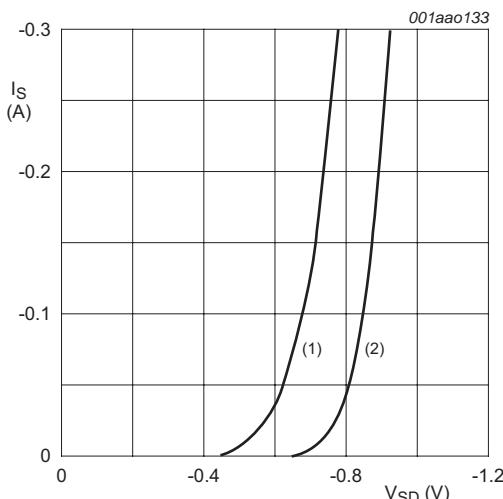
V_{GS} = 0 V
(1) T_j = 150 °C
(2) T_j = 25 °C

Fig 16. Source current as a function of source-drain voltage; typical values

8. Test information
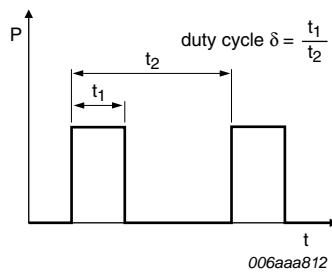
Fig 17. Duty cycle definition

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

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9. Package outline

Plastic surface-mounted package; 3 leads **SOT416**
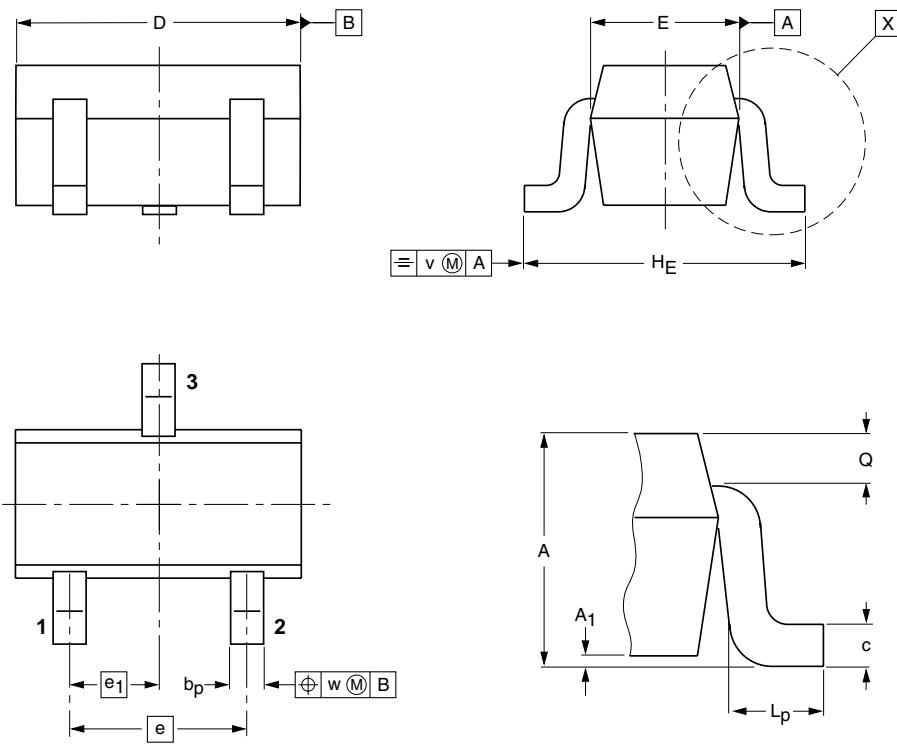

DIMENSIONS (mm are the original dimensions)

UNIT	A	A₁ max	bp	c	D	E	e	e₁	H_E	L_p	Q	v	w
mm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT416			SC-75			04-11-04 06-03-16

Fig 18. Package outline SOT416 (SOT416)

10. Soldering
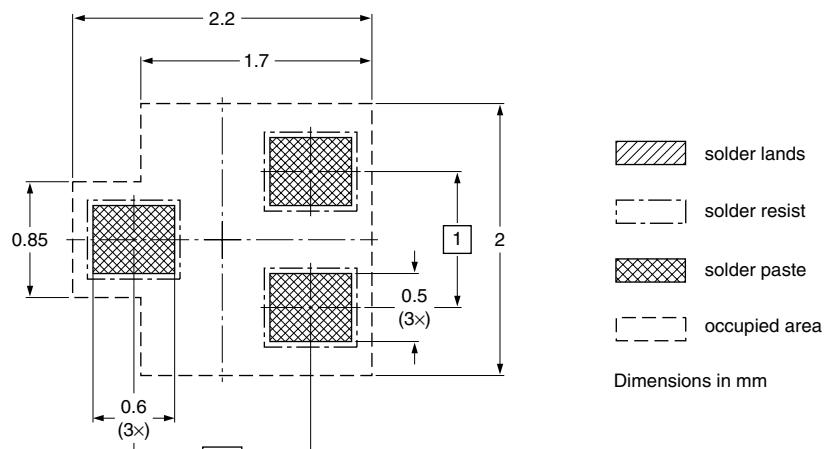
Fig 19. Reflow soldering footprint for SOT416 (SOT416)

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11. Revision history

Table 8.   **Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BSS84AKT v.1	20110523	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status [1] [2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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